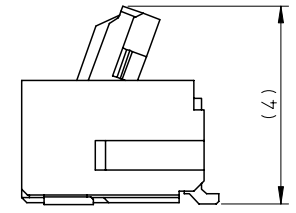
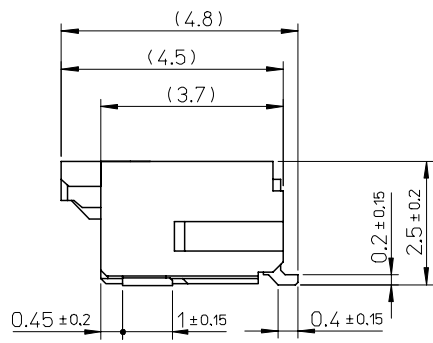
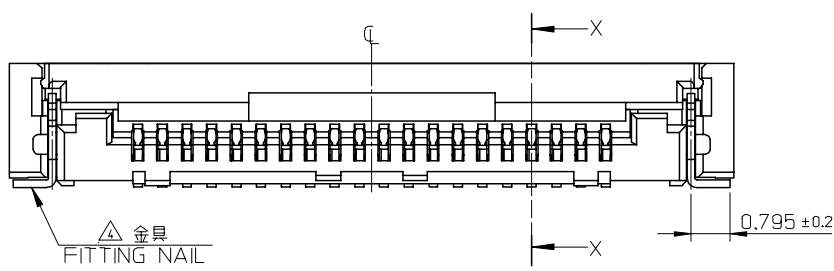
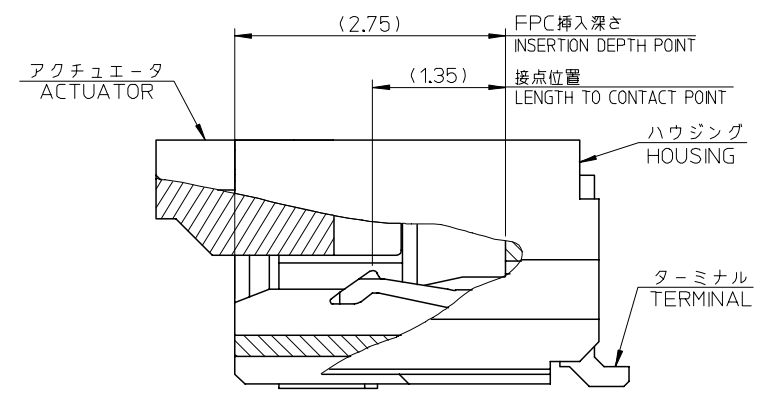
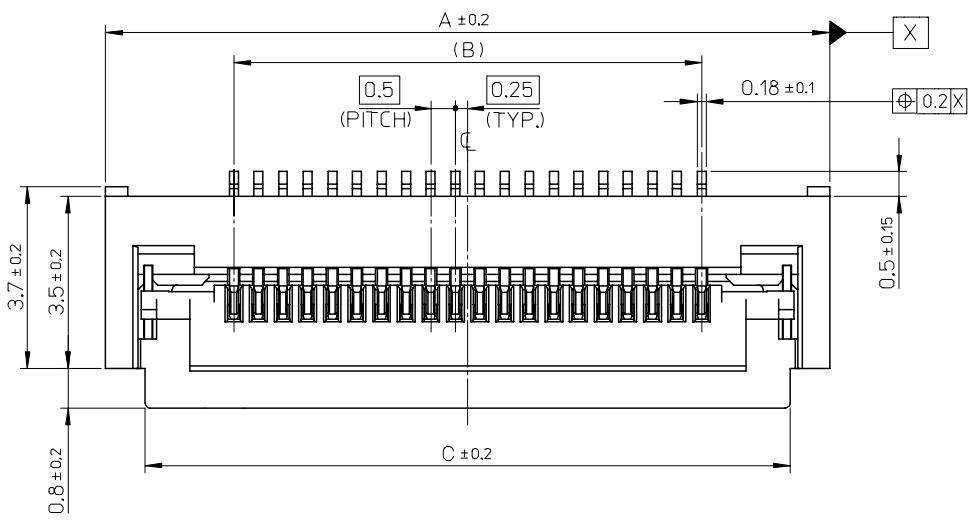


10 9 8 7 6 5 4 3 2 1

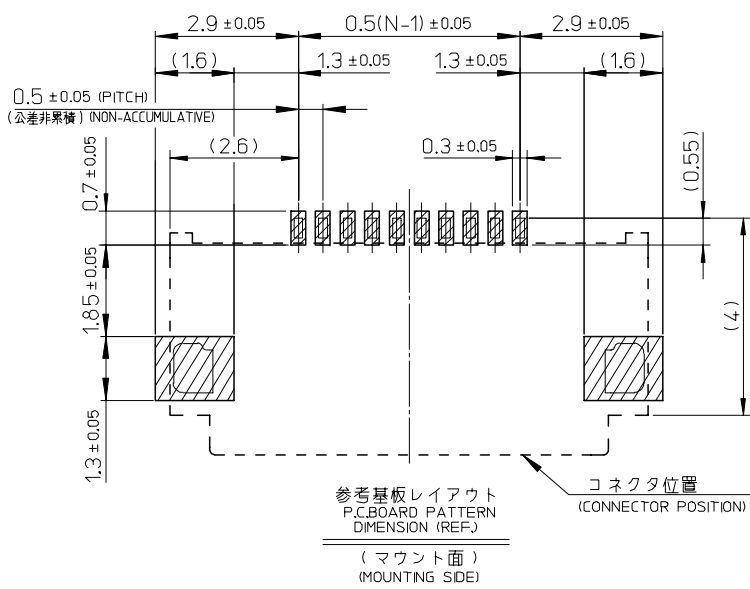
F  
E  
D  
C  
B  
A



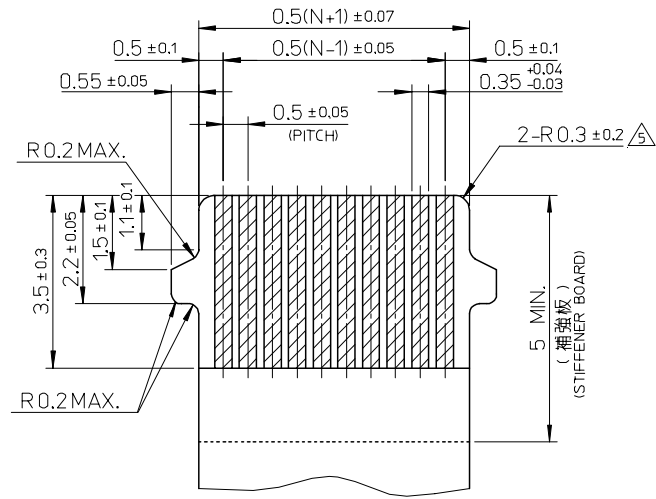
アクチュエータを開口した状態  
(WHEN ACTUATOR IS OPENED)

40.1	36.5	41.7	502500-7411	74
38.1	34.5	39.7	502500-7011	70
C	B	A	MATERIAL NO.	CIRCUIT

REVISED EC NO: J2007-3430 DRWN: AOYAGI CHKD: YMAEDA APPR: NUKITA	DESCRIPTION 2007/06/15 2007/06/18 2007/06/18	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	± ---	DRAWN BY YTAKAYASU	DATE 2007/03/01	TITLE 0.5 FPC CONN. ZIF E/O HSG ASS'Y (H=2.5)				
		10 OVER 30 UNDER	± ---	CHECKED BY HIRATA	DATE 2007/03/01	MOLEX INCORPORATED				
		30 OVER	± ---	APPROVED BY MSASAO	DATE 2007/03/01	DOCUMENT NO. SD-502500-001 SHEET NO. 1 OF 2				
ANGULAR ± --- °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE						
SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION								



参考基板レイアウト  
P.C.BOARD PATTERN  
DIMENSION (REF.)  
(マウント面)  
(MOUNTING SIDE)  
コネクタ位置  
(CONNECTOR POSITION)



適合FPC推奨寸法  
APPLICABLE FPC  
RECOMMENDED DIMENSION  
(仕上がり厚さ: 0.3 ± 0.05)  
(THICKNESS: 0.3 ± 0.05)

**注記 NOTES**

1. 使用材料 MATERIAL  
ハウジング : 液晶ポリマー ガラス充填, UL94-V0(ベージュ)  
HOUSING LIQUID CRYSTAL POLYMER GLASS FILLED, UL94V-0(BEIGE)  
アクチュエータ : PPS ガラス充填, UL94-V0(茶)  
ACTUATOR PPS GLASS FILLED, UL94V-0(BROWN)  
ターミナル : リン青銅(t=0.18)  
TERMINAL PHOSPHOR BRONZE  
金具 : リン青銅(t=0.15)  
FITTING NAIL PHOSPHOR BRONZE
2. めっき仕様 PLATING  
ターミナル TERMINAL  
ニッケル下地金めっき  
GOLD(Au) OVER NICKEL(Ni) PLATING.  
  
金具 FITTING NAIL  
ニッケル下地金めっき  
TIN(Sn) OVER NICKEL(Ni) PLATING.
3. エンボスタープ梱包時は、アクチュエータが閉じた状態とする。  
IN THE PACKAGE, ACTUATOR OF PART 502500-\*\*\*11 SHOULD BE CLOSED.
4. パターン剥離止め用金具  
FITTING NAIL FOR PREVENTION OF PEELING OF P.C.B. PATTERN.

- △ R0.3は、FPC 導体部にかからないこと。  
R0.3 MUST NOT BE OVERLAPPED TO PATTERN OF FPC.
6. N: 極数 N: CIRCUIT.
  7. ELV及びRoHS適合品  
ELV AND RoHS COMPLIANT

**FPC について:**

打ち抜き方向は導体側から補強板側を推奨します。  
導体部については軟銅箔35μmまたは50μmを推奨します。  
補強フィルム材質はポリイミドを推奨します。ベースフィルムは25μmを推奨します。  
接着剤は熱硬化接着剤を推奨します。  
尚、接着剤の接点部への付着は導通不良の原因になりますので、染み出しが無い様お願い致します。

ABOUT FPC  
RECOMMENDED PUNCHER DIRECTION : FROM CONDUCTOR SIDE TO STIFFENER FILM SIDE.  
RECOMMENDED CONDUCTOR SPEC :  
THICKNESS OF SOFT COPPER FOIL : 35 MICROMETER OR 50 MICROMETER.  
RECOMMENDED MATERIAL/THICKNESS.  
STIFFENER FILM : POLYIMIDE  
BASE FILM THICKNESS : 25μm  
BONDING AGENT : THERMOSETTING BONDING AGENT  
PLEASE PUT APPROPRIATE AMOUNT OF ADHESIVE ON ADHEREND BECAUSE THERE IS A POSSIBILITY THAT THE EXTRA ADHESIVE CAUSES THE DEFECT IN ELECTRICAL CONTINUITY.

REVISED EC NO: J2007-3430 DRWN: AOYAGI CHKD: MAEDA APPR: NUKITA	DESCRIPTION 2007/06/15 2007/06/18 2007/06/18	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		10 UNDER	± ---	DRAWN BY YTAKAYASU	DATE 2007/03/01	TITLE 0.5 FPC CONN. ZIF E/0 HSG ASS'Y (H=2.5)		
		10 OVER 30 UNDER	± ---	CHECKED BY HIRATA	DATE 2007/03/01	APPROVED BY MSASAO		
		30 OVER	± ---	APPROVED BY MSASAO	DATE 2007/03/01	MOLEX INCORPORATED		
A	REV	ANGULAR	± --- °	MATERIAL NO.	DOCUMENT NO.	SHEET NO.		
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE SHEET 1	SD-502500-001	2 OF 2		
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION								